

PCI
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1110/94326

PATENT

Re U.S. Patent Application

Applicant: Takashi YOKOYAMA et al.

Serial No.: 10/534,946

Filed: May 11, 2005

For: SILICON WAFER, ITS MANUFACTURING
METHOD, AND ITS MANUFACTURING
APPARATUS

)
) Confirmation No.: 3657
)
) I hereby certify that this correspondence is
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Gerald T. Shekleton

Gerald T. Shekleton Reg. No. 27,466

Response to Office Action dated June 14, 2007

Mail Stop AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

In response to the Office Action dated June 14, 2007 the following amendments and
remarks are made thereto: